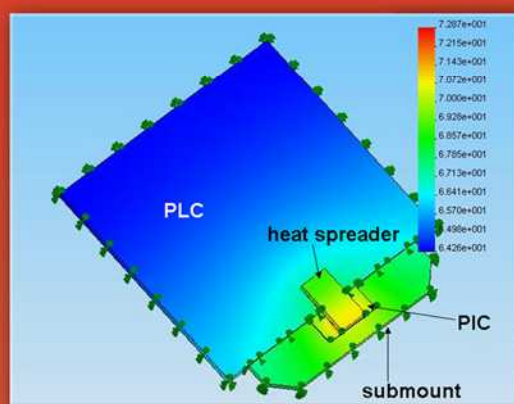
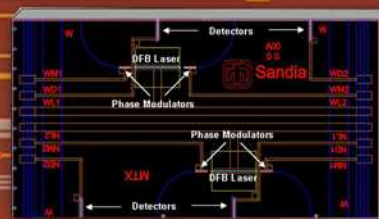


Preliminary Thermal Model of PIC-PLC chip Sub-assembly (DFB Laser Dissipation is Approx. 600mW)

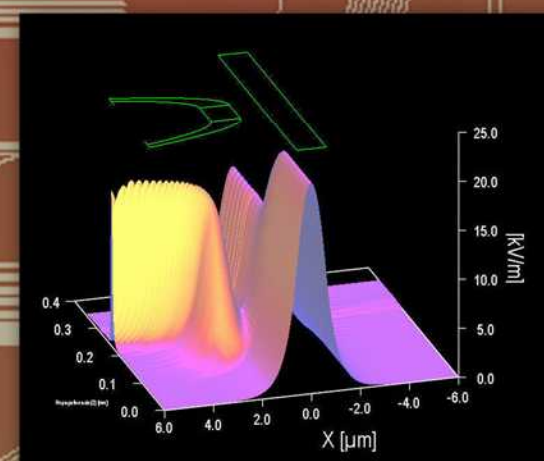
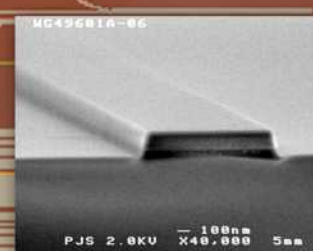
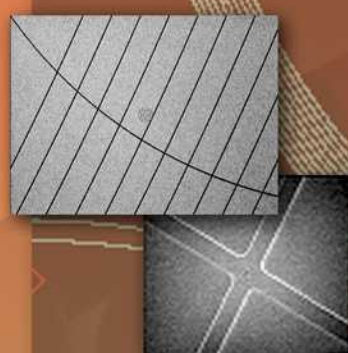
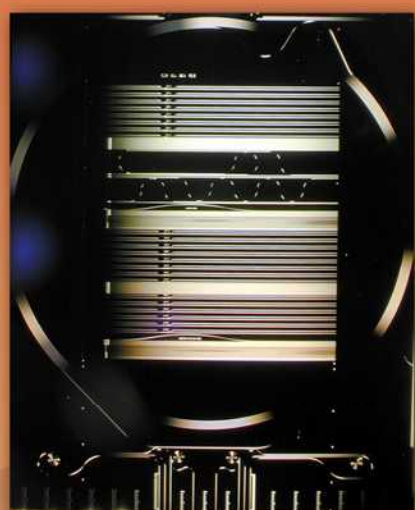


Photonic Integrated Circuit Structural Details



Development Team

PLANAR Light Circuit Details



Simulation
Results



MEMS Resonant Micro Optical Gyroscope (RMOG)



Packaging Concept for RMOG with Electronics

Conceptual Packaging Design for an Inertial Measurement System

